



YOUSHANG SEMICONDUCTOR

**设计研发新型功率器件**

**各类小信号开关**

**中低压及高压大电流等场效应管**

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## Product Summary

$BV_{DSS}$	$R_{DS(on)}$	$I_D$ $T_A = +25^\circ C$
60V	$0.33\Omega @ V_{GS} = 10V$	2.1A

## Features and Benefits

- $BV_{DSS} = 60V$
- $R_{DS(on)} = 0.33\Omega$

## Description and Applications

This MOSFET is designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- DC-DC converters
- Solenoids/relay driver for automotive applications
- Stepper motor drivers

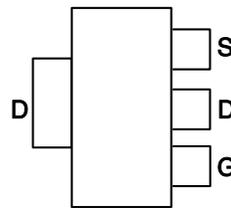
## Mechanical Data

- Package: SOT223 (Type DN)
- Package Material: Molded Plastic, UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 
- Weight: 0.112 grams (Approximate)

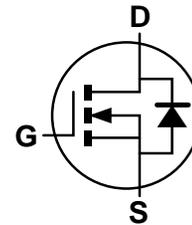
SOT223(Type DN)



Top View



Pin Out - Top View



Equivalent Circuit

**Maximum Ratings** (@  $T_A = +25^\circ\text{C}$ , unless otherwise stated.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	2.1	A
Pulsed Drain Current	$I_{DM}$	15	A
Power Dissipation	$P_{tot}$	3	W
Avalanche Current-Repetitive	$I_{AR}$	1	A
Avalanche Energy-Repetitive	$E_{AR}$	25	mJ
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

**Electrical Characteristics** (@  $T_A = +25^\circ\text{C}$ , unless otherwise stated.)

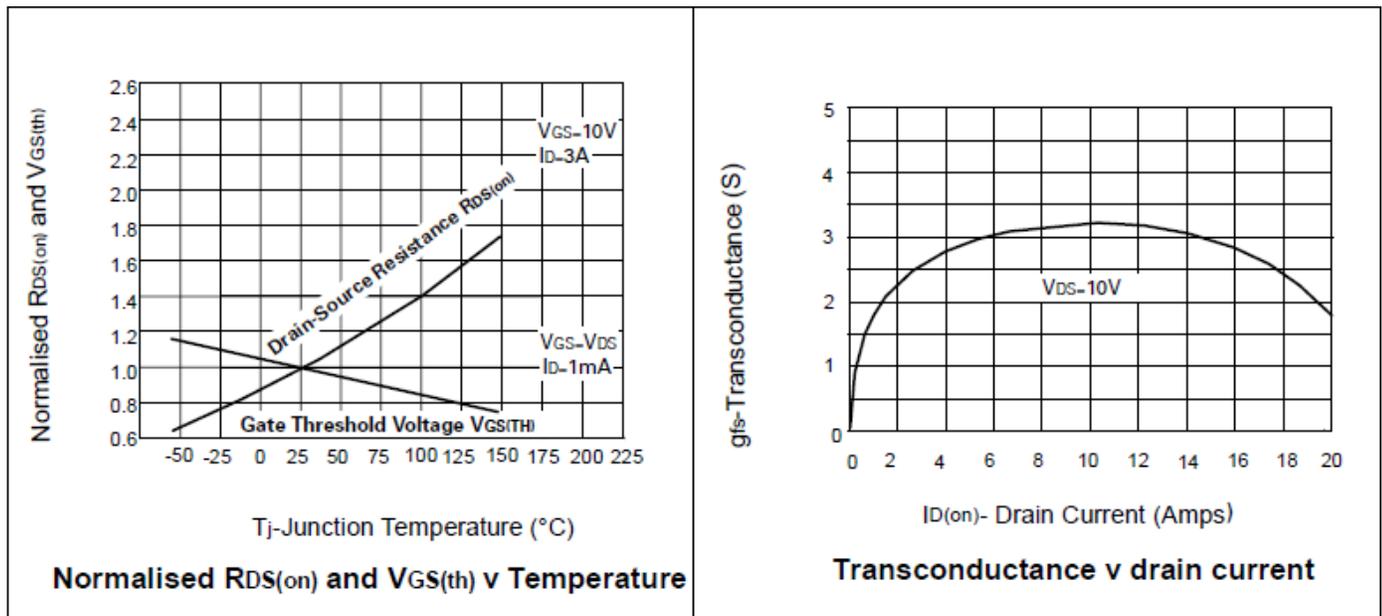
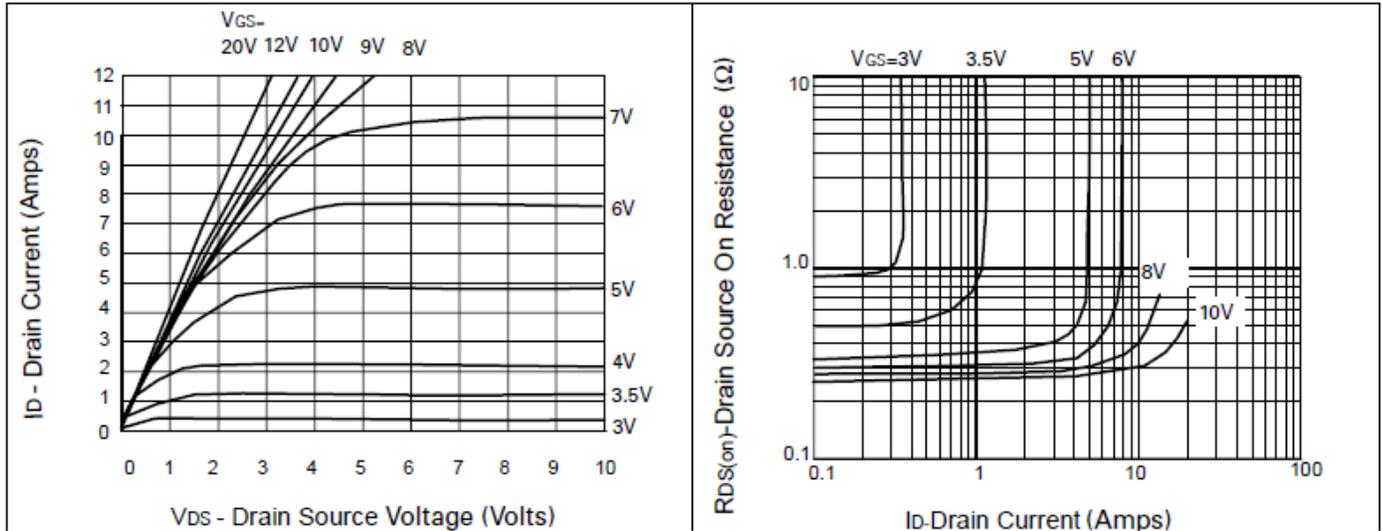
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	60	-	-	V	$V_{GS} = 0V, I_D = 1mA$
Zero Gate Voltage Drain Current	$I_{DSS}$	-	-	10 100	$\mu A$ $\mu A$	$V_{DS} = 60V, V_{GS} = 0V$ $V_{DS} = 48V, V_{GS} = 0V, T = +125^\circ\text{C}$ (Note 6)
Gate-Body Leakage	$I_{GSS}$	-	-	20	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
On-State Drain Current (Note 5)	$I_{D(on)}$	12	-	-	A	$V_{GS} = 10V, V_{DS} = 10V$
<b>ON CHARACTERISTICS</b>						
Gate-Source Threshold Voltage	$V_{GS(th)}$	1.3	-	3	V	$V_{DS} = V_{GS}, I_D = 1mA$
Static Drain-Source On-State Resistance (Note 5)	$R_{DS(on)}$	-	0.22	0.33	$\Omega$	$V_{GS} = 10V, I_D = 3A$
		-	0.32	0.45	$\Omega$	$V_{GS} = 5V, I_D = 1.5A$
Forward Transconductance (Notes 5, 6)	$g_{fs}$	0.7	-	-	S	$V_{DS} = 25V, I_D = 3A$
<b>DYNAMIC CHARACTERISTICS</b>						
Input Capacitance (Note 6)	$C_{iss}$	-	-	350	pF	$V_{DS} = 25V, V_{GS} = 0V,$ $f = 1.0MHz$
Common Source Output Capacitance (Note 6)	$C_{oss}$	-	-	140	pF	
Reverse Transfer Capacitance (Note 6)	$C_{rss}$	-	-	30	pF	
Turn-On Delay Time (Notes 6, 7)	$t_{D(on)}$	-	-	8	ns	$V_{DD} \approx 25V, V_{GEN} = 10V, I_D = 3A$
Rise Time (Notes 6, 7)	$t_R$	-	-	25	ns	
Turn-Off Delay Time (Notes 6, 7)	$t_{D(off)}$	-	-	30	ns	
Fall Time (Notes 6, 7)	$t_F$	-	-	16	ns	

**Drain-Source Diode Characteristics**

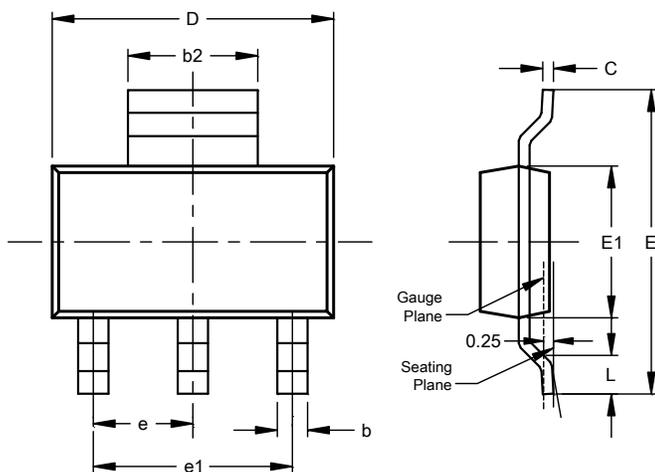
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Diode Forward Voltage (Note 5)	$V_{SD}$	-	0.82	-	V	$I_S = 0.32A, V_{GS} = 0$
Reverse Recovery Time	$T_{RR}$	-	112	-	ns	$I_F = 0.32A, V_{GS} = 0, I_R = 0.1A$

- Notes:
5. Measured under pulsed conditions. Width=300 $\mu s$ . Duty cycle  $\leq 2\%$
  6. Sample test.
  7. Switching times measured with 50 $\Omega$  source impedance and <5ns rise time on a pulse generator. Spice parameter data is available upon request for this device.

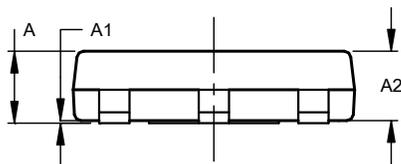
Typical Characteristics



### Package Outline Dimensions

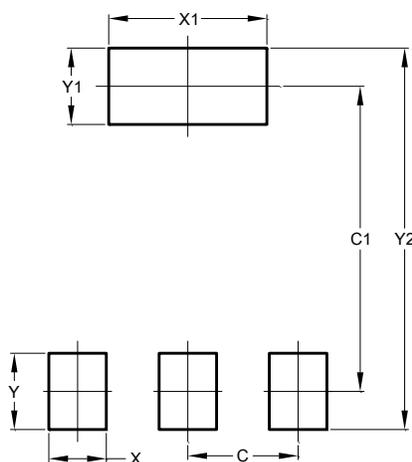


SOT223 (Type DN)			
Dim	Min	Max	Typ
A	--	1.70	--
A1	0.01	0.15	--
A2	1.50	1.68	1.60
b	0.60	0.80	0.70
b2	2.90	3.10	--
c	0.20	0.32	--
D	6.30	6.70	--
E	6.70	7.30	--
E1	3.30	3.70	--
e	--	--	2.30
e1	--	--	4.60
L	0.85	--	--
All Dimensions in mm			



### Suggested Pad Layout

SOT223 (Type DN)



Dimensions	Value (in mm)
C	2.30
C1	6.40
X	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00